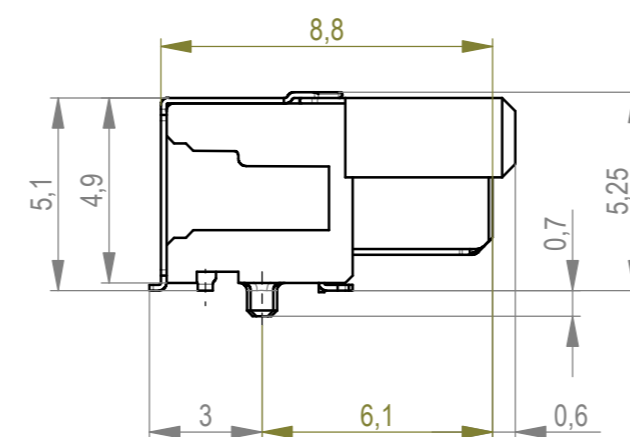
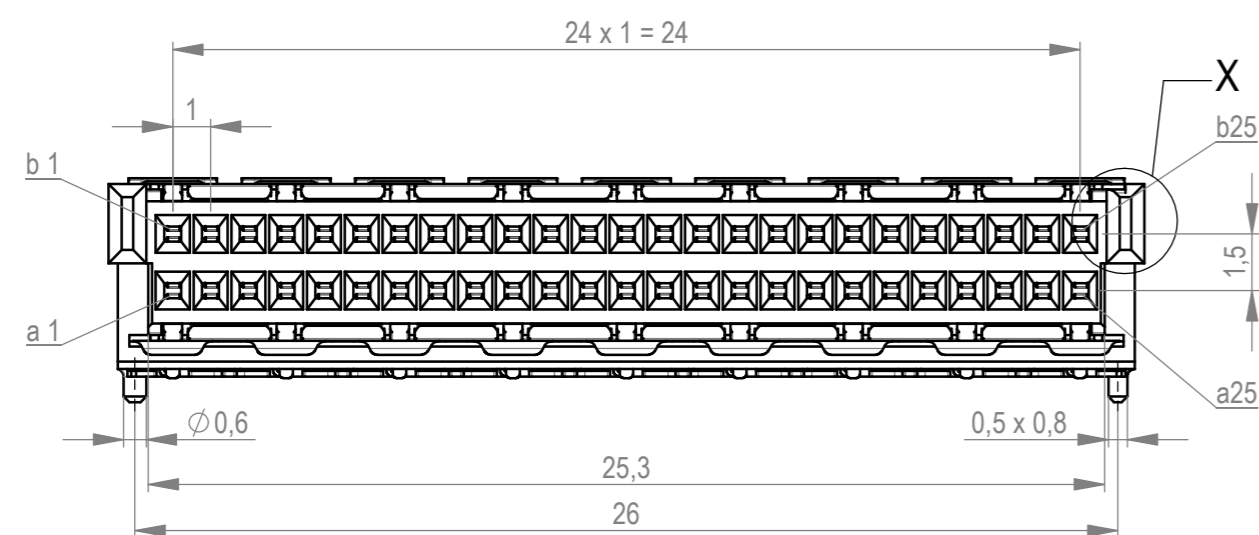
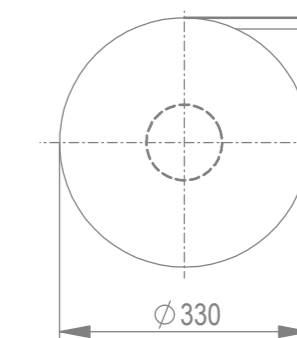
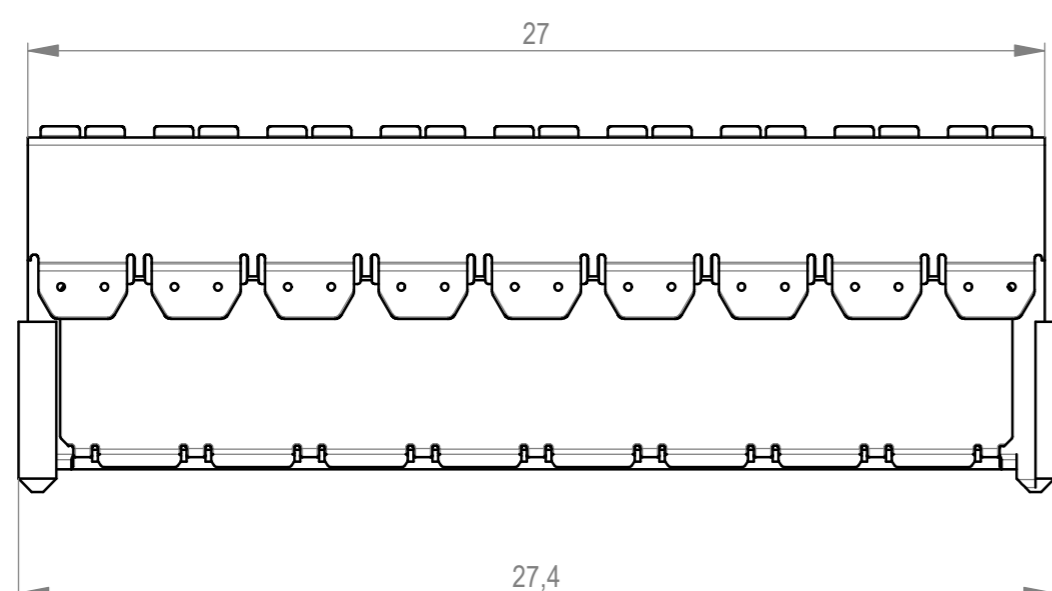
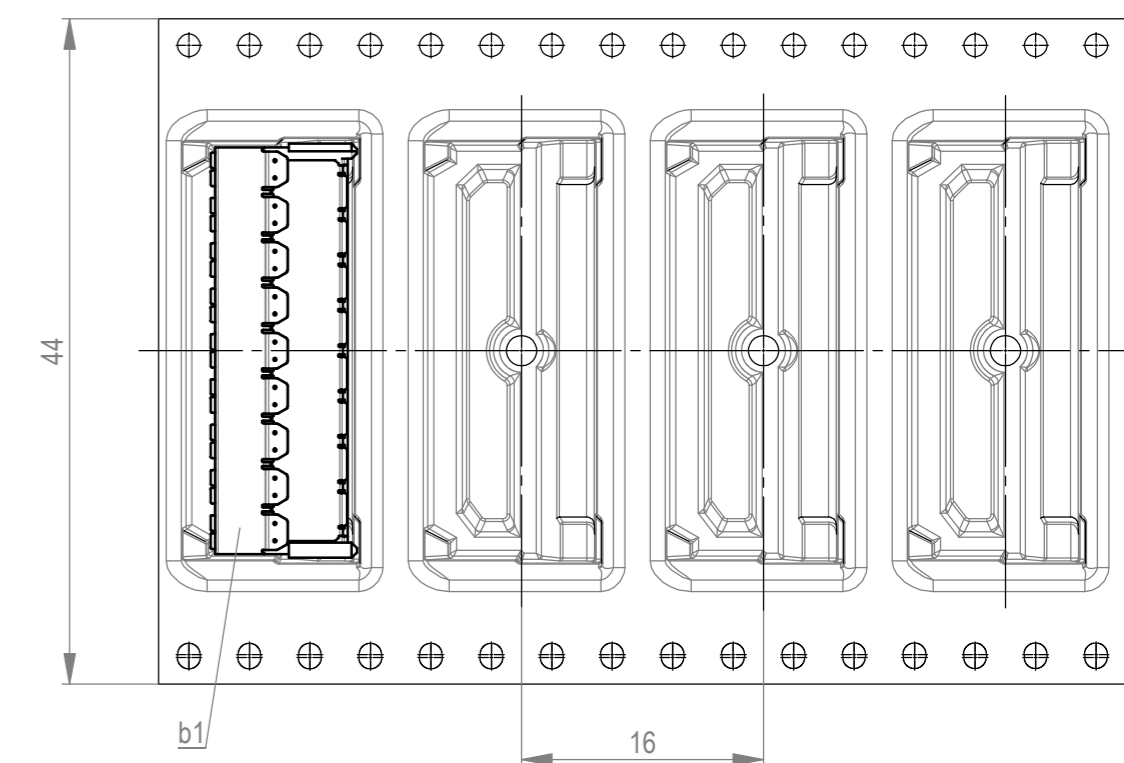


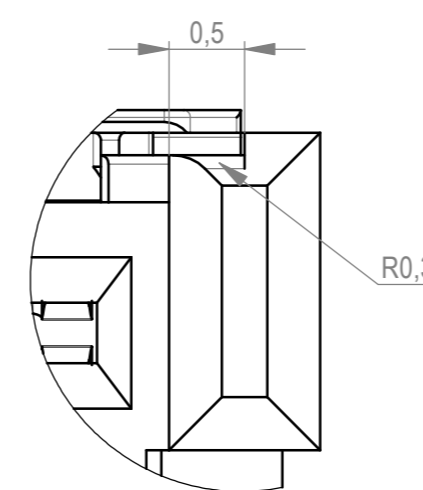
Verpackt im Gurt in Anlehnung an DIN IEC 60286-3
 tape on reel packaging according to DIN IEC 60286-3
 Verpackungseinheit: 500 Stück
 packaging unit: 500 pcs



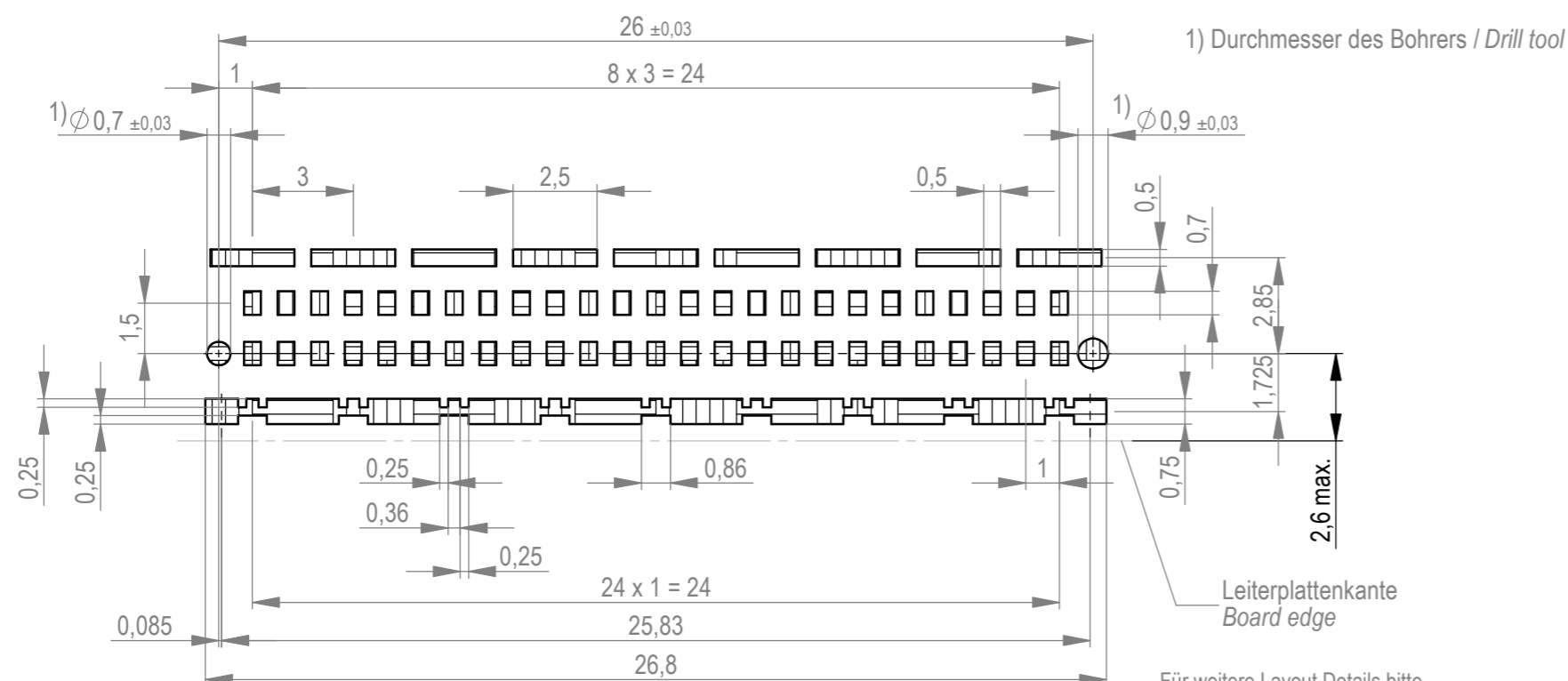
Abspulrichtung - reel off direction →



Einzelheit X
 M 20:1



Leiterplatten-Layout Vorschlag / PCB-Layout Proposal



Für weitere Layout Details bitte
 Applikations Schrift MicroSpeed beachten.
 For further layout details please consider
 MicroSpeed application note.

Anforderungsstufe 1
 performance level 1

Kontaktbereich vergoldet
 mating area gold plating

Anschlussbereich verzinkt 4-6 µm
 terminal area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm
 coplanarity area of termination ≤ 0,1 mm

Weder die deutsche Version dieser Zeichnung noch die englische Originalversion sind verbindlich, wenn nicht ausdrücklich genehmigt. Zwischenänderungen verpflichten zu Schadenersatz.
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Die deutsche Version dieser Zeichnung dient nur zur Einreichung der Handlung. Bei Abweichungen vom englischen Original gilt das englische Original. This drawing has been created for convenience only and may deviate from the English original.
 The German version of this drawing is only for submission purposes and may deviate from the English version. All rights reserved.

Dimension no.	Tolerances	Scale 5:1 Material	ISO 8015	All Dimensions in mm
Customer drawing: This Drawing is a controlled Document.	Subject to modification without prior notice. Drawing will not be updated.		Federl. 90° 50p. BM SMD EMV Female 90° 50 c. BM SMD EMV	
h1	18.05.2023	TE Connectivity		C
Index	Date	Class		A2
		MSPEED		